

<b>Product Specification [产品规格书]:</b>	Document No	PS-3004-01
<b>Subject [主题]:</b>	Date Issued	2020/5/19
3.00mm Pitch 3004 Series Connector Specification	Date Revised	2020/5/19
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This specification is referred to the 3.00mm series wire to board connector

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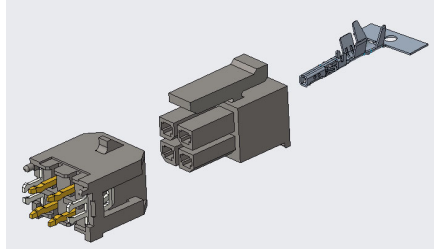
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**【1.适用范围 Scope】**

此种规格包括 3.00mm Pitch 3004 Series 连接器规格说明。

This Specification Covers the 3.00mm Pitch 3004 Series Connector Specification.

**【2.规格与料号 Spec and Part number】**

规格内容 Specification	产品料号 Production No.	产品图示 Picture of Product
端子/Terminal	3004THF-HSN1	
胶壳/Housing	3004HM-2*XX-N0HFBK	
针座/Wafer	3004WV-2xXXPHF-LPSW1BT	

**【3.材质与表面处理 Disposal of Material and surface】**

规格内容 Specification	材质 Materials	表面处理 Disposal of Surface
端子/Terminal	高导铜/C7025-TM02	亮锡 100~180u" ;镍底 50~100u"
胶壳/Housing	PA66	/
针座/Wafer	空壳: LCP 四方针: 高导铜/C1100 鱼叉: 黄铜/C2680	镍底 50u"Min, 雾锡 100u"Min

(上述参数请以工程图为准/Please Refer to the Project drawing for the above Specification)

**【4. 额定等级 Ratings and applicable wires】**

项目【Item】	规格【Standard】								
4-1. 额定电压 Rated Voltage (Max.)	250V								[AC/DC]
4-2. 额定电流 Rated Current (Max.)		2PIN	3~4PIN	5~8PIN	9~10PIN	11~12PIN	13~18PIN	19~24PIN	
	#16	12.5A	12A	10.5A	10A	9A	8.5A	8A	
	#18	10.5A	10A	10A	8A	8A	7.5A	7A	
4-3. 使用温度范围 Ambient temperature Range	-40°C~+105°C								
4-4. 适用线径 Applicable wire insulation O.D	AWG#16~18								

【 \*升温时含端子.Including terminal temperature rise. 】

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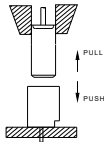
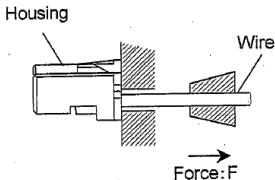
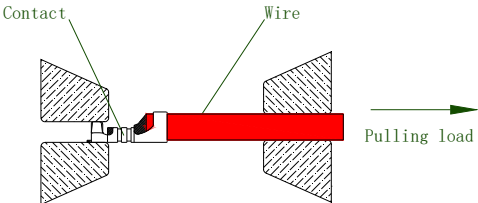
**【5.性能 PERFORMANCE】**

**5-1. 电气的性能 Electrical Performance.**

项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】
5-1-1	接触阻抗 Contact Resistance	公母配合,开放电压 20mV 以下,电流 10mA 检测连接器 A~B 区. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A).	Initial: 10 milliohms Max. After Test: ΔR 20 milliohms Max.
5-1-2	绝缘阻抗 Insulation Resistance	公母配合,在相邻端子,端子与地片之间,使用 500V 的直流电,检测连接器. Mate connectors, apply 500V DC between adjacent terminal or ground. (Based upon EIA-364-21B / MIL-STD-202 Method 302 Cond.B)	1000 Megohms Min.
5-1-3	耐电压 Dielectric Strength	公母配合,在相邻端子,端子与地片之间,使用 1000V 的交流电 1 分钟,检测连接器. Mate connectors, apply 1000V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A / MIL-STD-202 Method 301)	外观无损伤, 无打火花 No Breakdown and Flashover
5-1-4	铆线后端子接触阻抗 Contact resistance on crimped portion	铆线后之端子,开放电压 20mV 以下,电流 10mA 检测连接器. Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	10 milliohms Max.

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**5-2. 机械的性能 Mechanical Performance.**

项目 【Item】	条件 【Test Condition】	规格 【Requirement】
5-2-1 插拔力 Insertion & Withdraw Force	<p>以每分钟 25.4±3mm 的速率插入和拔出。 Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute.</p> 	<p>插入力 Insertion force: 8N Max./Per Pin</p> <p>拔出力 Withdraw force: 2N Min./Per Pin</p>
5-2-2 端子保持力 Terminal/ Housing Retention Force	<p>以每分 25.4±3mm 的速率,将端子从 Housing 内轴向拔出的力量。 Apply axial pull out force at the speed rate of 25.4±3mm/minute on the terminal assembled in the housing.</p> 	24.5N Min.
5-2-3 端子插入力 Terminal Insertion Force	<p>铆线后之端子插入 Housing 所需最大力量。 Insert the crimped terminal into the housing.</p>	14.7N Max.
5-2-4 PIN 针保持力 Terminal/Housing Retention Force	<p>以每分 25.4±3mm 的速率,将端子从本体内轴向拔出的力量。 Apply axial push force at the speed rate of 25.4±3mm/minute.</p>	13.7N Min.
5-2-5 端子压着强度 (Crimped connections)	<p>固定铆线后的端子, 使电线与端子分离时所需的最小力量。 Fix the crimped terminal, apply axial pull out force on the wire. (Do not crimp insulation part).</p> 	AWG#16~#18: 57.8N Min.
5-2-6 公母座带卡扣保持 力 Male/Female Housing Retention Force	<p>将插好端子的公母座含卡扣以每分钟 25±6mm 的速度拔出所需要力量。 Mate connectors and apply pull-out force at the speed rate of 25 ± 6mm/min. This Test should be done with positive lock locked.</p>	68.4N Min

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项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】	
5-3-1	重复插拔 Repeated Insertion/ Withdrawal	以每分钟不超过 10 次的速率,将公母插拔 30 次。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
5-3-2	温升测试 Temperature Rise	公母连接器配合后, 加载额定电流直到温度上升到稳定状态, 然后再测量温升 (EIA364-70,Method) Mating connectors shall be energized at rating current until thermal stability is achieved, and then measured the temperature rise. (EIA364-70,Method)	温升 Temperature rise	30°C Max.
5-3-3	振动测试 Vibration test	振幅: 1.5mm P-P 时间: 10~55~10 HZ in 1 minute 持续时间: 每轴向 2 小时 Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.
5-3-4	冲击测试 Shock test	在 X.Y.Z 上 6 个方向上,以 490m/s2(50g 的力量)冲击下各 3 回.490m/s2{50G}, 3 strokes in each X.Y.Z. axes. (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.

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**5-3. 环境性能及其它 Environmental Performance and Others.**

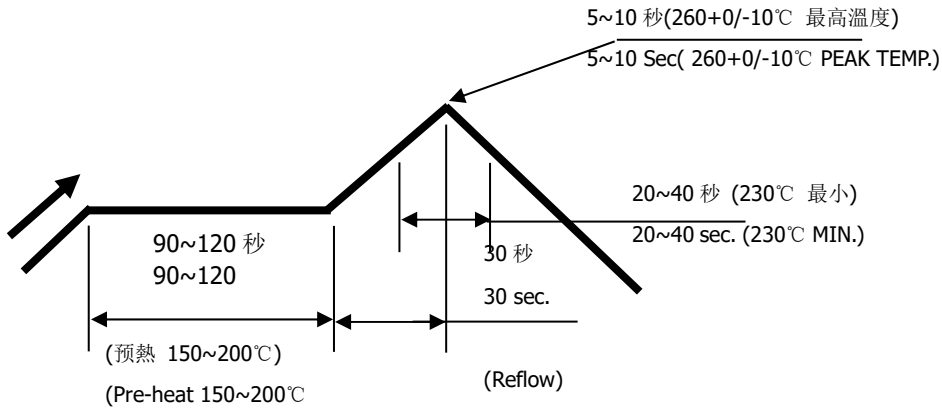
项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】	
5-3-5	耐热性 Heat Resistance	105±2°C, 240 hours. (Based upon MIL-STD-202 Method 108A Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
5-3-6	耐寒性 Cold Resistance	-40±2°C, 96 hours. ( Based upon EIA-364-105) ( Based upon EIA-364-105)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
5-3-7	耐湿性 Humidity	温度: 40±2°C 湿度: 90~95%(RH) 持续时间: 96 hours Temperature: 40±2°C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
			耐电压 Dielectric Strength	500V AC/1 分钟
			绝缘阻抗 Insulation Resistance	1000 Megohms Min.
5-3-8	温度变化 Temperature Cycling	从-40°C持续 30 分钟升至+105°C持续 30 分钟,循环 5 次. 5 cycles of: a) -40°C 30 minutes. b) +105°C 30 minutes. (Based upon EIA-364-32B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
5-3-9	盐水喷雾 Salt Spray	在温度 35±2°C, 盐水浓度 5±1% 下, 盐水喷雾 48±1 小时. 48±1 hours exposure to a salt spray from the 5±1% solution at 35±2°C. (Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B).	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	△R20 milliohms Max.
5-3-10	焊锡附着性 Solder-ability	焊接时间: 5±0.5 秒. 焊接温度: 245±5°C. Soldering time: 5±0.5sec solder. temperature: 245±5°C.	Solder Wetting	浸渍面积需 95% 以上 95% of immersed area must show no voids, pin holes.

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5-3-11	焊锡耐热性 Resistance to Soldering Heat	焊接时间: 5~10 秒. 焊接温度: 260+0/-10°C. Soldering time:5~10 sec solder. Temperature:260+0/-10°C. (Based upon EIA-364-56A)	外观 Appearance	无异状 No Damage
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**【6. SMT 回流条件 SMT REFLOW CONDITION】**



温度条件曲线图/ 基板上温度

TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON BOARD PATTERN SIDE)

注记: 由于 P.C 板等焊接装置改变条件,所以请预先用自己的装置检查回流焊的条件。

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.